LNJ115W8RRA1

Surface Mounting Chip LED

TSS-2 Type

■ Absolute Maximum Ratings $T_a = 25$ °C

• Yellow Green

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	55	mW	
Forward current	I_{F}	20	mA	
Pulse forward current *	I_{FP}	60	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

• Orange

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Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

• Yellow Green

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *	Io	$I_F = 10 \text{ mA}$	9	15		mcd
Reverse current	I _R	$V_R = 4 V$			100	μΑ
Forward voltage	V _F	$I_F = 10 \text{ mA}$		2.03	2.50	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$		575		nm
Dominant emission wavelength	λ_{d}	$I_F = 10 \text{ mA}$		572		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		15		nm

Note) *: Measurement tolerance: ±20%

• Orange

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *	I _O	$I_F = 10 \text{ mA}$	17	32		mcd
Reverse current	I_R	$V_R = 4 V$			100	μΑ
Forward voltage	V _F	$I_F = 10 \text{ mA}$		2.00	2.50	V
Peak emission wavelength	λ_{P}	$I_F = 10 \text{ mA}$		630		nm
Dominant emission wavelength	λ_{d}	$I_F = 10 \text{ mA}$		620		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		15		nm

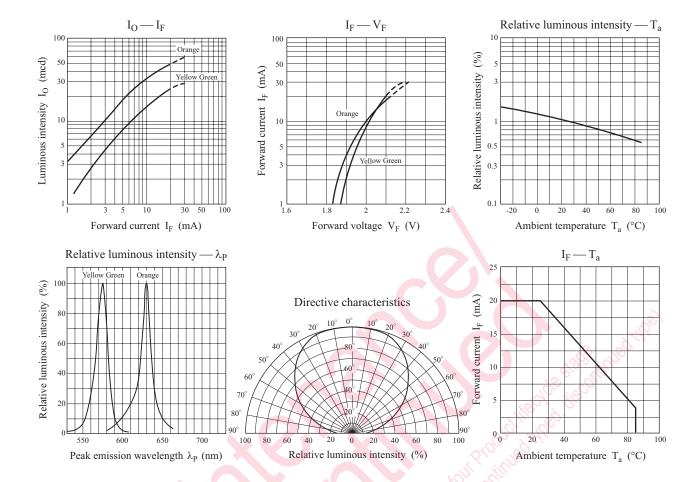
Note) *: Measurement tolerance: ±20%

■ Lighting Color

- Yellow Green
- Orange

LNJ115W8RRA1

Panasonic

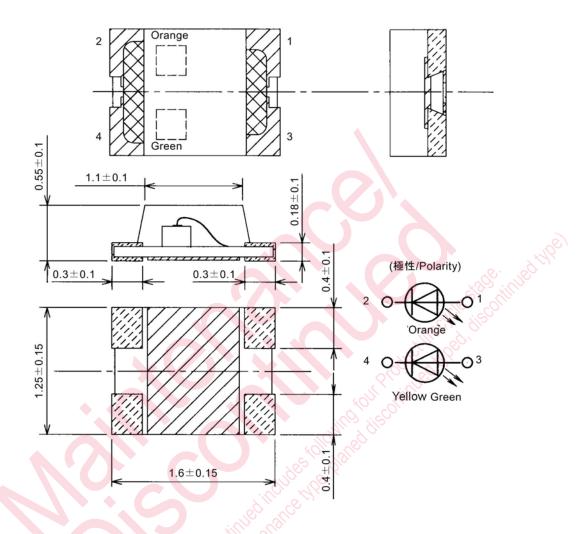


2 SHD00718BEK

Panasonic LNJ115W8RRA1

■ Package (Unit: mm)

KLTFTN4K1540



- Pin name
 - 1, 3: Anode
 - 2, 4: Cathode

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